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(12) **United States Design Patent**
Kinoshita et al.

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(54) **POLISHING PAD FOR SUBSTRATE POLISHING APPARATUS**

(71) Applicant: **EBARA CORPORATION**, Tokyo (JP)

(72) Inventors: **Masaki Kinoshita**, Tokyo (JP); **Toshifumi Kimba**, Tokyo (JP)

(73) Assignee: **EBARA CORPORATION**, Tokyo (JP)

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; 257/E21.001, E21.002, 257/E21.21, E21.23; 361/230, 233, 234; 451/64, 65, 66, 67, 72, 259, 278, 285, 451/286, 287, 288, 290
See application file for complete search history.

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Primary Examiner — Elizabeth J Oswecki
(74) *Attorney, Agent, or Firm* — Pearne & Gordon LLP

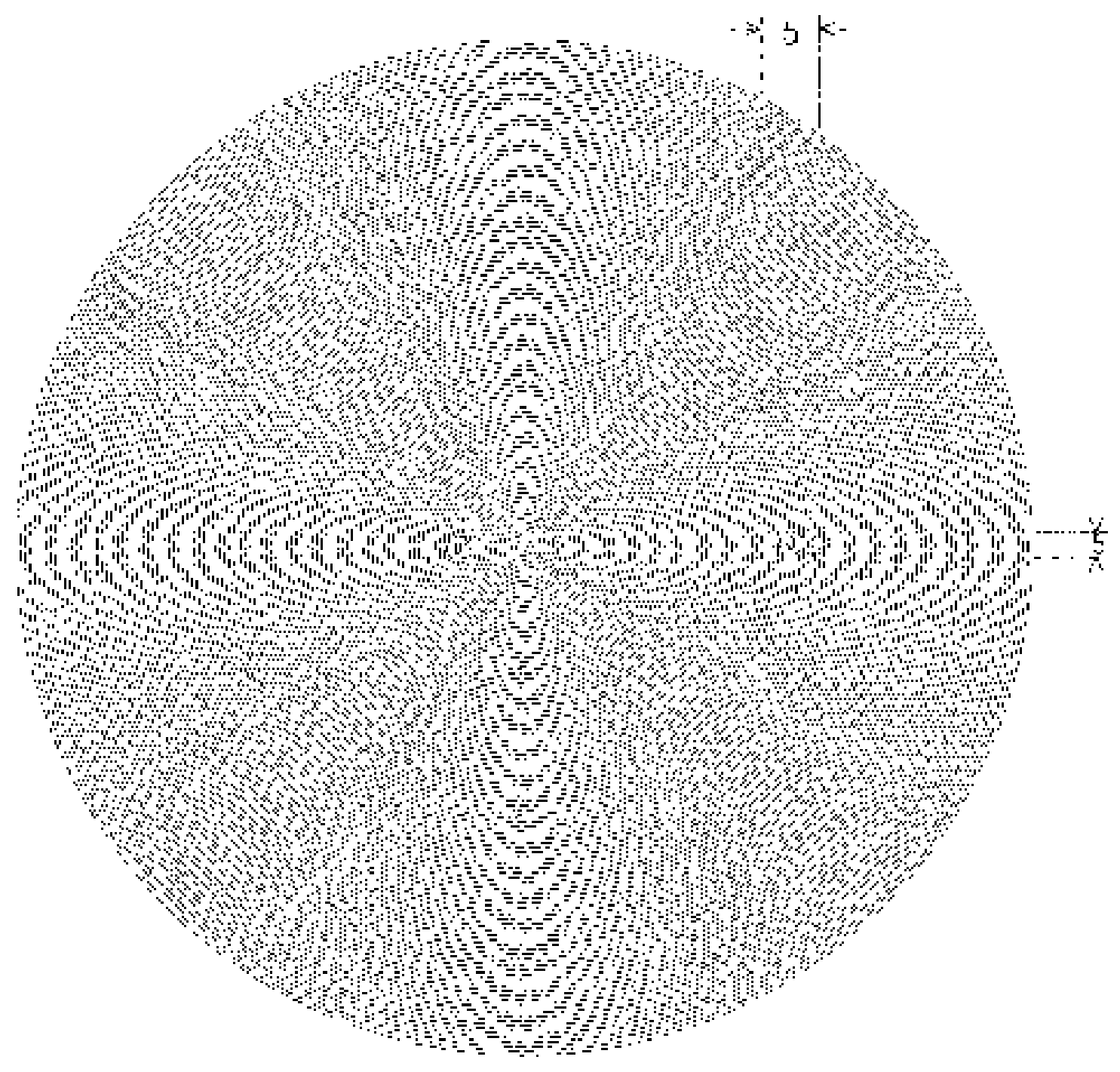
(57) **CLAIM**

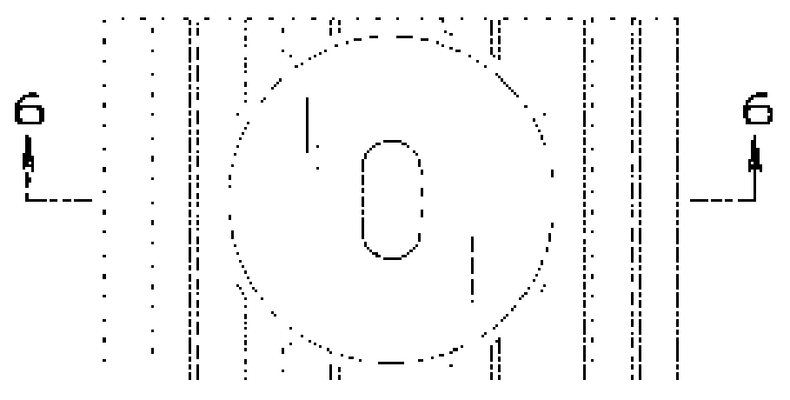
The ornamental design for a polishing pad for substrate polishing apparatus, as shown and described.

DESCRIPTION

FIG. **1** is a top plan view of a first embodiment of a polishing pad for substrate polishing apparatus, showing our new design;
FIG. **2** is a bottom plan view thereof;
FIG. **3** is a front view thereof, the rear view being identical;
FIG. **4** is a right side view thereof, the left side view being identical;
FIG. **5** is an enlarged, top plan view thereof, taken along lines **5-5** of FIG. **1**;
FIG. **6** is an enlarged, cross-sectional view thereof, taken along lines **6-6** of FIG. **5**;
FIG. **7** is a top plan view of a second embodiment of a polishing pad for substrate polishing apparatus, showing our new design;
FIG. **8** is a bottom plan view thereof;
FIG. **9** is a front view thereof, the rear view being identical;
FIG. **10** is a right side view thereof, the left view being identical;
FIG. **11** is an enlarged, partial top plan view thereof, taken along lines **11-11** of FIG. **7**; and,
FIG. **12** is an enlarged, cross-sectional view thereof, taken along lines **12-12** of FIG. **11**.
The dashed-dot-dashed lines represent the boundary lines of the claimed design. The even dashed broken lines depict environment subject matter only and form no part of the claimed design.

1 Claim, 9 Drawing Sheets





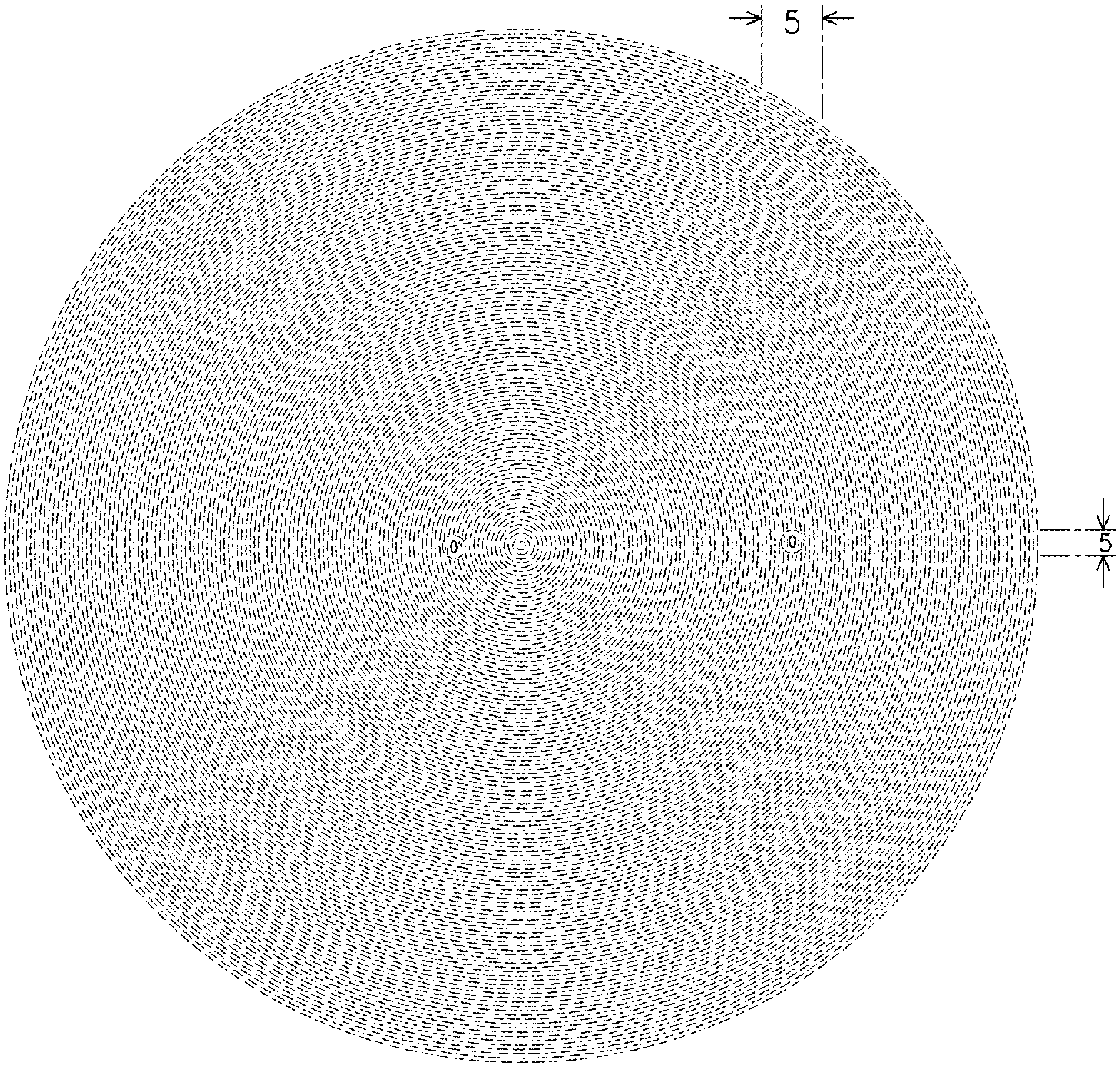


FIG. 1

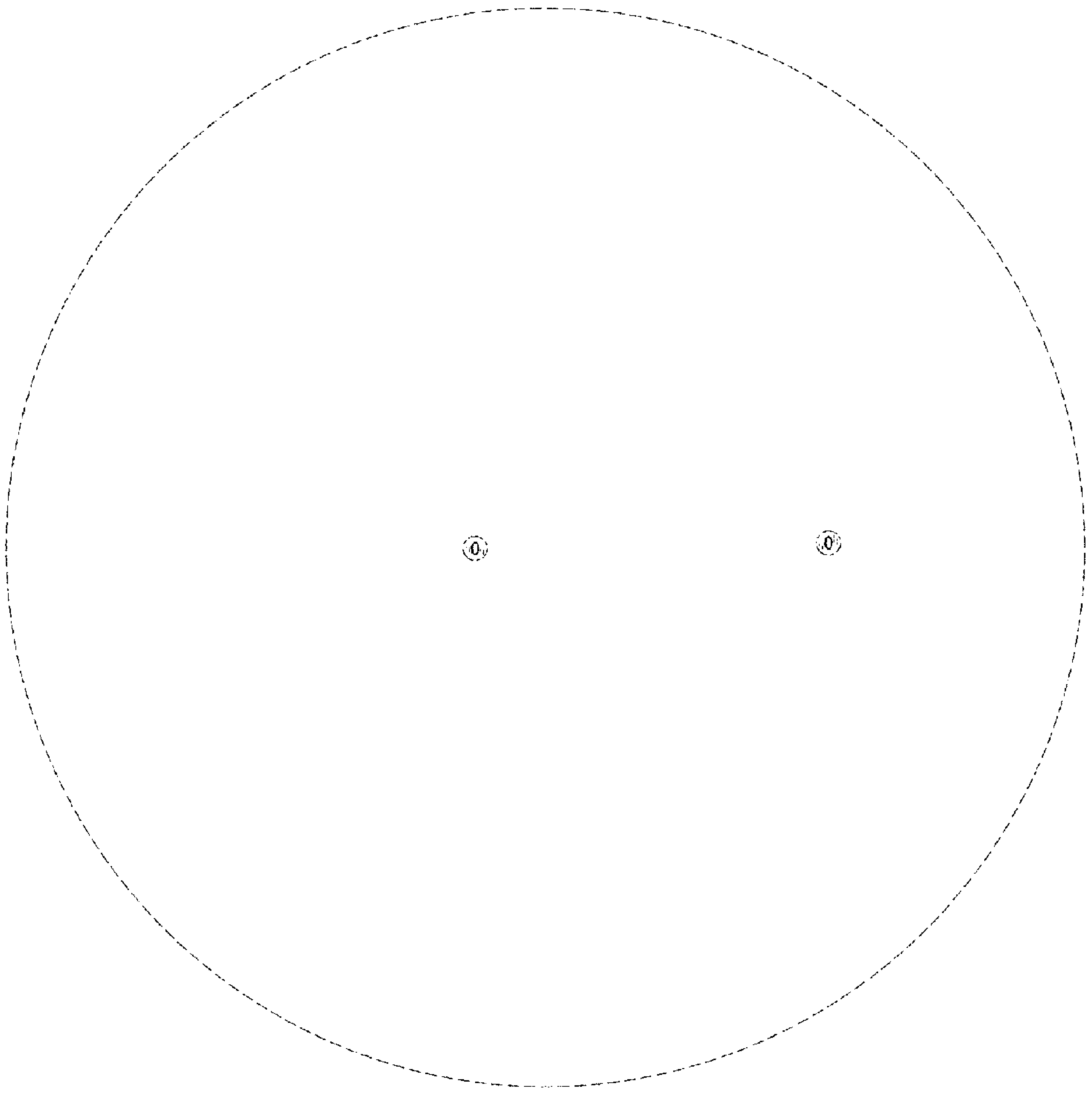


FIG. 2

FIG. 3

FIG. 4

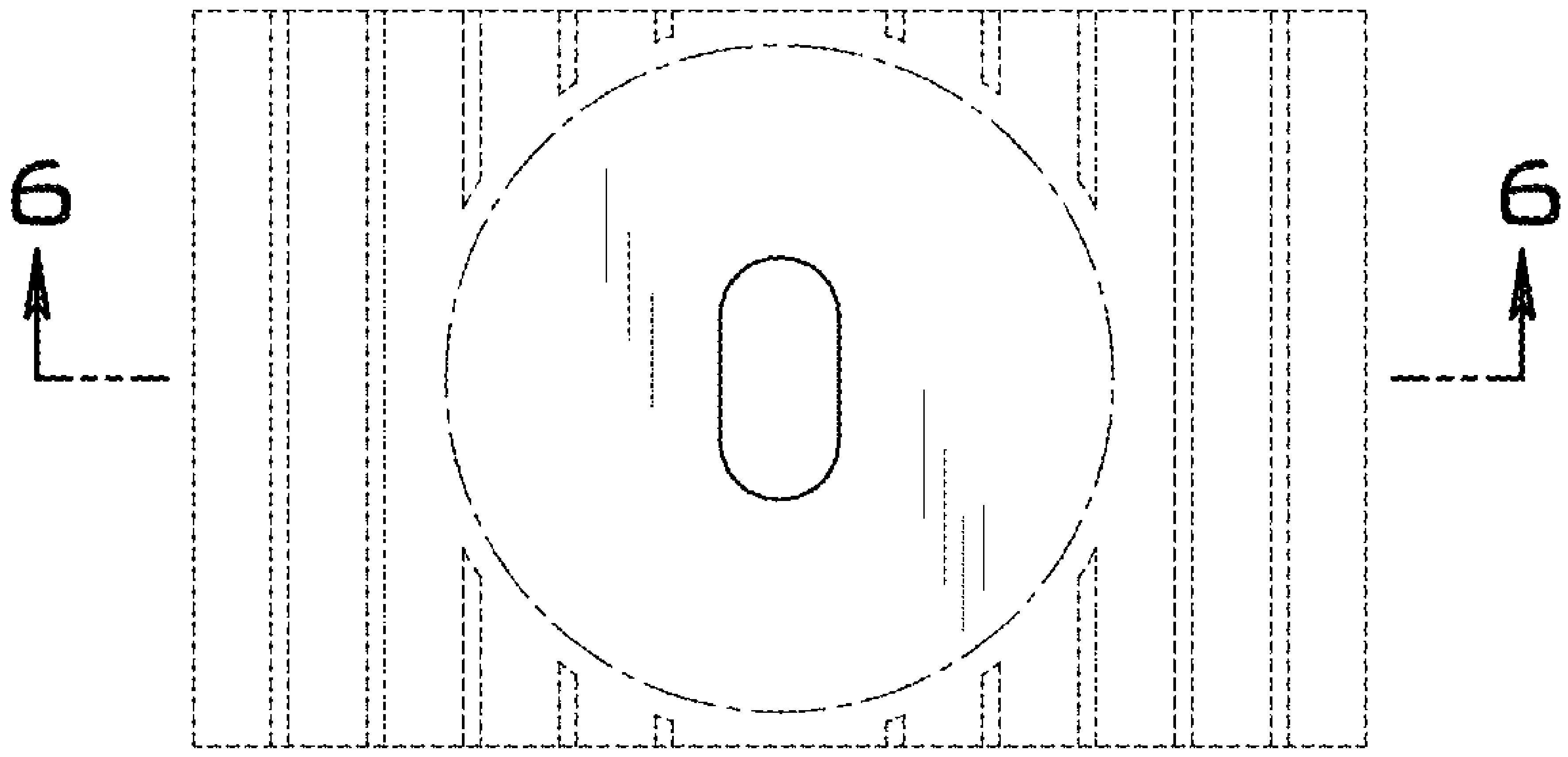


Fig. 5

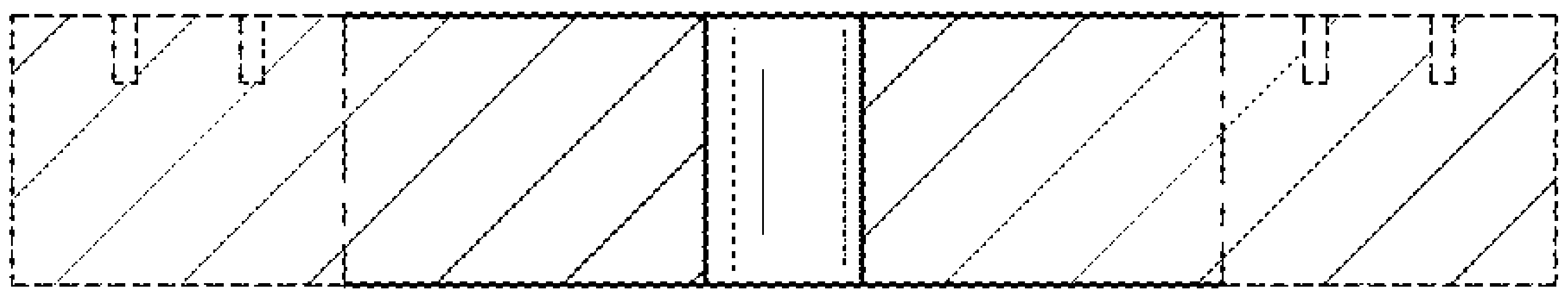


Fig. 6

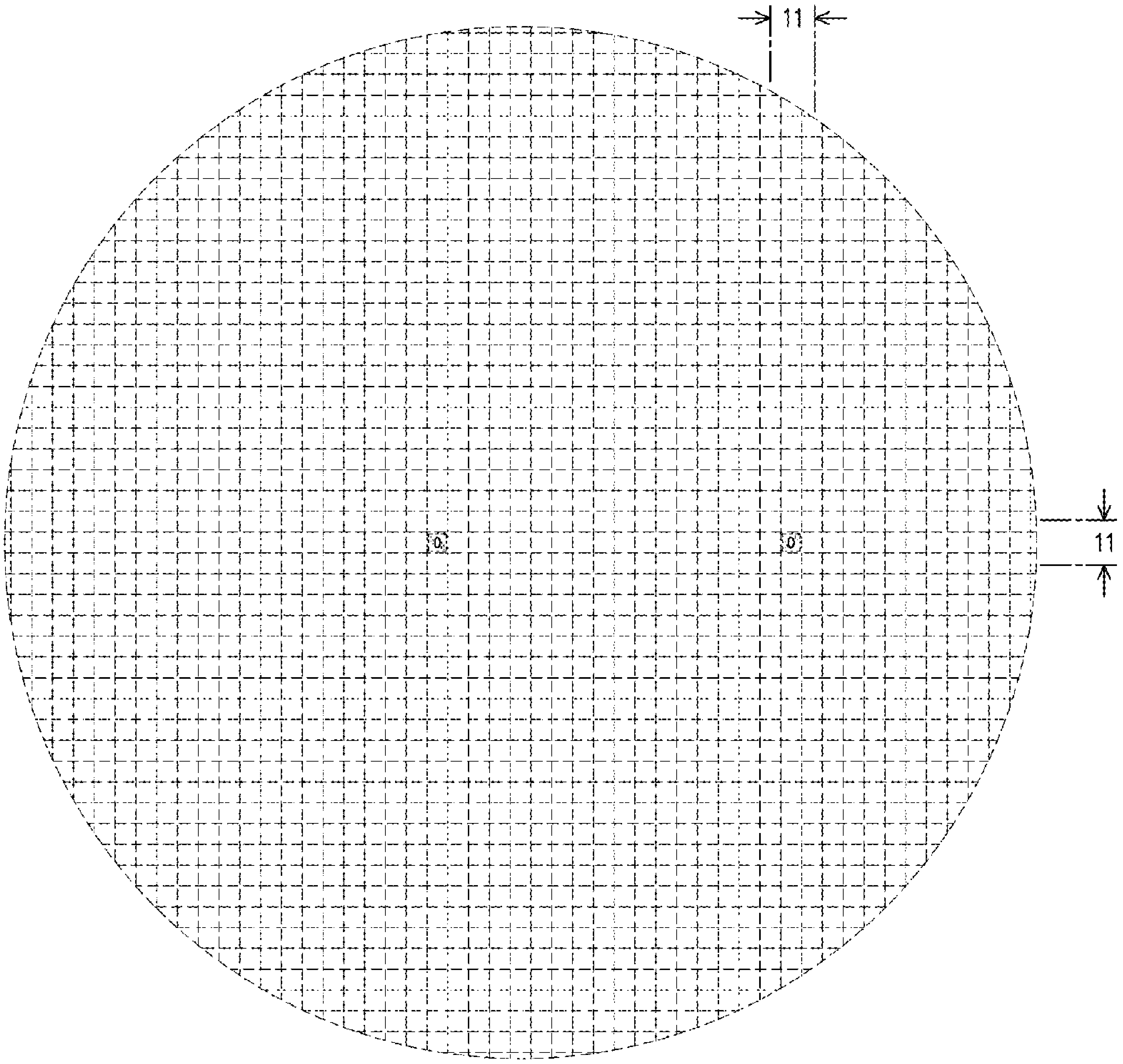


FIG. 7

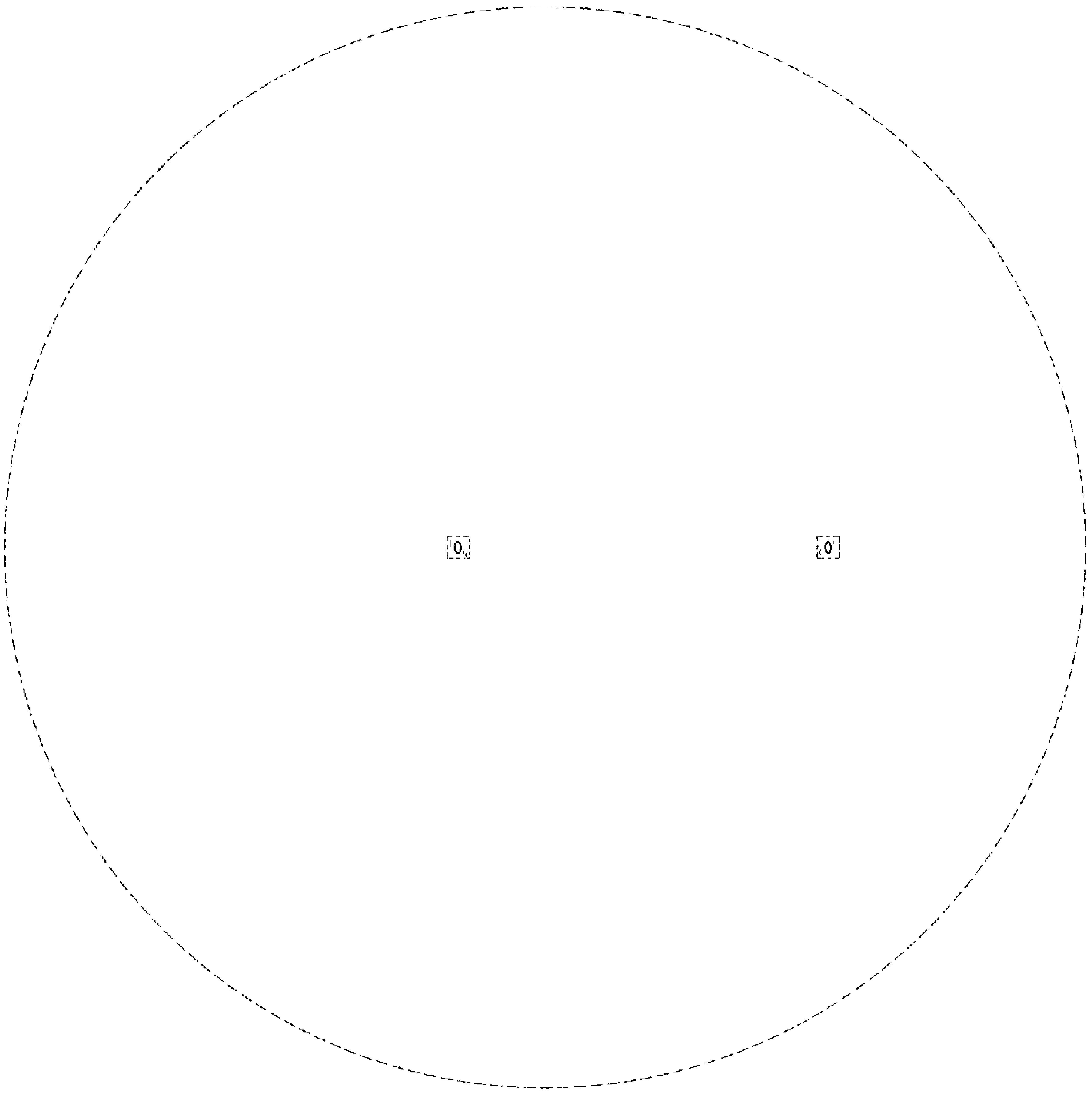


FIG. 8

Fig. 9

Fig. 10

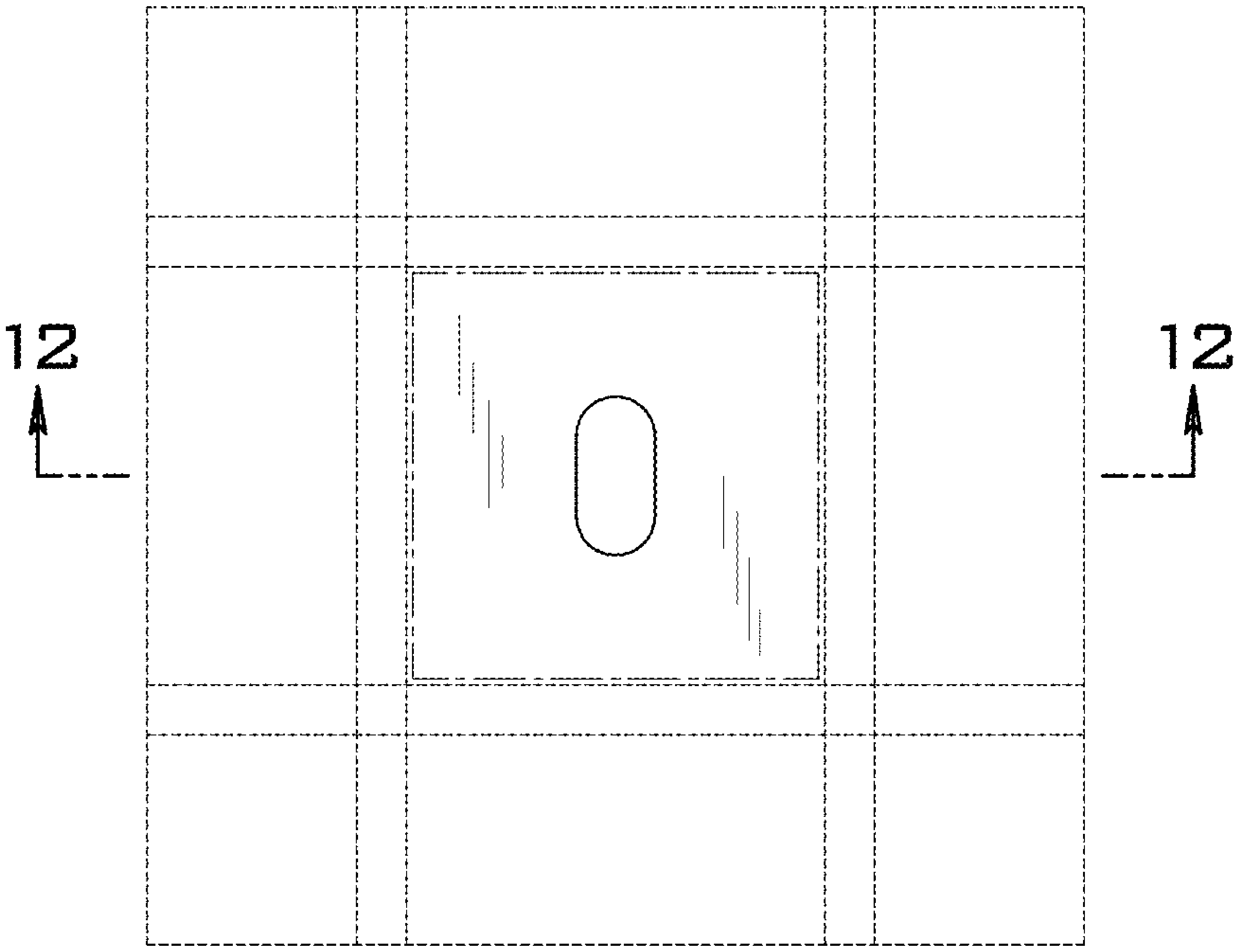


FIG. 11

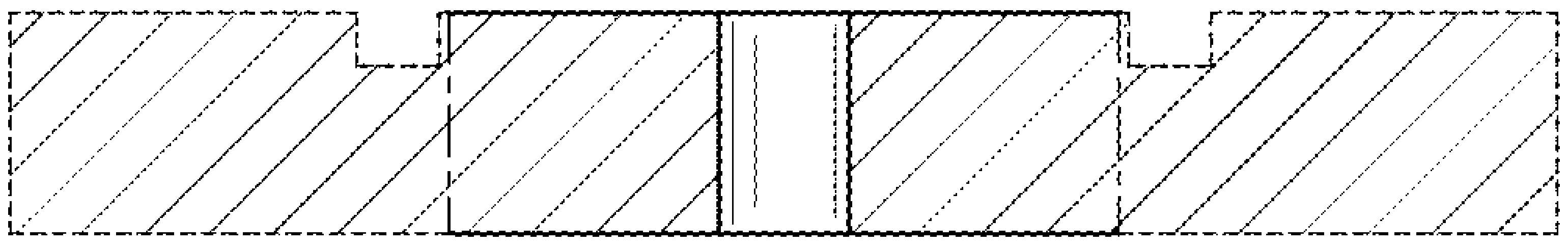


FIG. 12